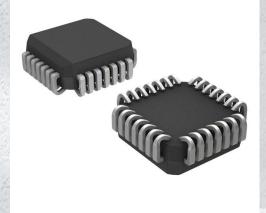


# MC10H645FN Datasheet

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DiGi Electronics Part Number MC10H645FN-DG

Manufacturer onsemi

Manufacturer Product Number MC10H645FN

Description IC CLK BUFFER 2:9 28PLCC

Detailed Description Clock Fanout Buffer (Distribution), Multiplexer IC 2:

9 28-LCC (J-Lead)



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# **Purchase and inquiry**

Manufacturer Product Number:	Manufacturer:
MC10H645FN	onsemi
Series:	Product Status:
	Obsolete
Type:	Number of Circuits:
Fanout Buffer (Distribution), Multiplexer	1
Ratio - Input:Output:	Differential - Input:Output:
2:9	Yes/Yes
Input:	Output:
Input: TTL	Output: TTL
TTL	πL
TTL Voltage - Supply:	TTL Operating Temperature:
TTL Voltage - Supply: 4.75V ~ 5.25V	TTL Operating Temperature: 0°C ~ 85°C
TTL  Voltage - Supply:  4.75V ~ 5.25V  Mounting Type:	Operating Temperature:  0°C ~ 85°C  Package / Case:

# **Environmental & Export classification**

8542.39.0001

RoHS Status:	Moisture Sensitivity Level (MSL):
RoHS non-compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	

### 2:1:9 TTL Clock Driver

#### Description

The MC10H645 is a single supply, low skew, TTL I/O 2:1:9 Clock Driver. Devices in the H600 clock driver family utilizes the PLCC–28 for optimal power and signal pin placement.

The device features a 24 mA TTL output stage with AC performance specified into a 50 pF load capacitance. A 2:1 input Mux is provided on chip to allow for distributing both system and diagnostic clock signals or designing clock redundancy into a system. With the SEL input held LOW the DO input will be selected, while the D1 input is selected when the SEL input is forced HIGH.

#### **Features**

- Low Skew Typically 0.65 ns Within Device
- Guaranteed Skew Spec 1.25 ns Part-to-Part
- Input Clock Muxing
- Differential ECL Internal Design
- Single Supply
- Extra TTL and ECL Power/Ground Pins
- These Devices are Pb-Free and are RoHS Compliant\*



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PLCC FN SUFFIX CASE 776

#### **MARKING DIAGRAM**



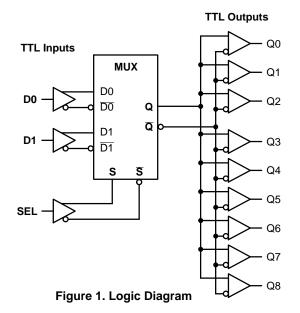
A = Assembly Location

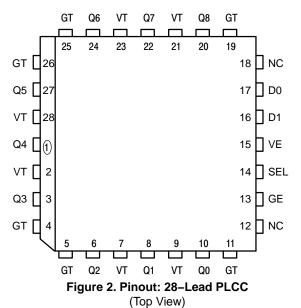
WL = Wafer Lot
 YY = Year
 WW = Work Week
 G = Pb-Free Package

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.





**Table 1. PIN NAMES** 

PIN	FUNCTION
GT VT VE GE Dn Q0 – Q8 SEL	TTL Ground (0 V) TTL V <sub>CC</sub> (+5.0 V) ECL V <sub>CC</sub> (+5.0 V) ECL Ground (0 V) TTL Signal Input TTL Signal Outputs TTL Mux Select

**Table 2. PIN DESCRIPTIONS** 

Pin	Symbol	Description	Pin	Symbol	Description
1	Q4	Signal Output (TTL)	15	VE	ECL V <sub>CC</sub> (+5.0 V)
2	VT	TTL V <sub>CC</sub> (+5.0 V)	16	D1	Signal Input (TTL)
3	Q3	Signal Output (TTL)	17	D0	Signal Input (TTL)
4	GT	TTL Ground (0 V)	18	NC	No Connection
5	GT	TTL Ground (0 V)	19	GT	TTL Ground (0 V)
6	Q2	Signal Output (TTL)	20	Q8	Signal Output (TTL)
7	VT	TTL V <sub>CC</sub> (+5.0 V)	21	VT	TTL V <sub>CC</sub> (+5.0 V)
8	Q1	Signal Output (TTL)	22	Q7	Signal Output (TTL)
9	VT	TTL V <sub>CC</sub> (+5.0 V)	23	VT	TTL V <sub>CC</sub> (+5.0 V)
10	Q0	Signal Output (TTL)	24	Q6	Signal Output (TTL)
11	GT	TTL Ground (0 V)	25	GT	TTL Ground (0 V)
12	NC	No Connection ´	26	GT	TTL Ground (0 V)
13	GE	ECL Ground	27	Q5	Signal Output (TTL)
14	SEL	Select Input (TTL)	28	VT	TTL V <sub>CC</sub> (+5.0 V)

**Table 3. TRUTH TABLE** 

D0	D1	SEL	Q
L H X X	X X L H	III	н н

Table 4. ABSOLUTE RATINGS (Do not exceed)

Symbol	Characteristic	Value	Unit
VE (ECL)	Power Supply Voltage	-0.5 to +7.0	V
VT (TTL)	Power Supply Voltage	-0.5 to +7.0	V
VI (TTL)	Input Voltage	-0.5 to +7.0	V
V <sub>out</sub>	Disabled 3-State Output	0.0 to V <sub>T</sub>	V
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
T <sub>amb</sub>	Operating Temperature	0.0 to +85	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 5. DC CHARACTERISTICS (VT = VE =  $5.0 \text{ V} \pm 5\%$ )

			<b>0</b> °	C.	25	°C	85	°C		
Symbol	Characterist	ic	Min	Max	Min	Max	Min	Max	Unit	Condition
I <sub>EE</sub>	Power Supply Current	ECL		30		30		30	mA	VE Pin
I <sub>CCH</sub>		TTL		30		30		30	mA	Total all VT pins
I <sub>CCL</sub>				35		35		35	mA	
V <sub>OH</sub>	Output HIGH Voltage		2.5 2.0		2.5 2.0		2.5 2.0		V	$I_{OH} = -3.0 \text{ mA}$ $I_{OH} = -15 \text{ mA}$
V <sub>OL</sub>	Output LOW Voltage			0.5		0.5		0.5	V	I <sub>OL</sub> = 24 mA
I <sub>OS</sub>	Output Short Circuit Cu	rrent	-100	-225	-100	-225	-100	-225	mA	V <sub>OUT</sub> = 0 V

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

Table 6. TTL DC CHARACTERISTICS (VT = VE =  $5.0 \text{ V} \pm 5\%$ )

		<b>0</b> °	C	25	°C	85	°C		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit	Condition
V <sub>IH</sub> V <sub>IL</sub>	Input HIGH Voltage Input LOW Voltage	2.0	0.8	2.0	0.8	2.0	0.8	V	
I <sub>IH</sub>	Input HIGH Current		20 100		20 100		20 100	μΑ	V <sub>IN</sub> = 2.7 V V <sub>IN</sub> = 7.0 V
I <sub>IL</sub>	Input LOW Current		-0.6		-0.6		-0.6	mA	V <sub>IN</sub> = 0.5 V
V <sub>OH</sub>	Output HIGH Voltage	2.5 2.0		2.5 2.0		2.5 2.0		V	$I_{OH} = -3.0 \text{ mA}$ $I_{OH} = -24 \text{ mA}$
V <sub>OL</sub>	Output LOW Voltage		0.5		0.5		0.5	V	I <sub>OL</sub> = 24 mA
V <sub>IK</sub>	Input Clamp Voltage		-1.2		-1.2		-1.2	V	$I_{IN} = -18 \text{ mA}$
Ios	Output Short Circuit Current	-100	-225	-100	-225	-100	-225	mA	V <sub>OUT</sub> = 0 V

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

Table 7. AC CHARACTERISTICS (VT = VE =  $5.0 \text{ V} \pm 5\%$ )

			0	°C	25	°C	85°C			
Symbol	Characteristic		Min	Max	Min	Max	Min	Max	Unit	Condition
t <sub>PLH</sub>	Propagation Delay D <sub>0</sub> to Output Only	Q0-Q8	4.8	5.8	4.8	5.8	5.2	6.2	ns	CL = 50 pF
t <sub>PLH</sub>	Propagation Delay D <sub>1</sub> to Output		4.8	5.8	4.8	5.8	5.2	6.2	ns	
t <sub>PHL</sub>	Propagation Delay D <sub>0</sub> to Output D <sub>1</sub> to Output		4.8 4.8	5.8 5.8	4.8 4.8	5.8 5.8	5.2 5.2	6.2 6.2	ns	
t <sub>skpp</sub>	Part-to-Part Skew D <sub>0</sub> to Output Only			1.0		1.0		1.0	ns	
t <sub>skwd</sub> *	Within-Device Skew D <sub>0</sub> to Output Only			0.65		0.65		0.65	ns	
t <sub>PLH</sub>	Propagation Delay SEL to Q	Q0-Q8	4.5	6.5	5.0	7.0	5.2	7.2	ns	CL = 50 pF
t <sub>r</sub> t <sub>f</sub>	Output Rise/Fall Time 0.8V to 2.0V	Q0-Q8	0.5 0.5	2.5 2.5	0.5 0.5	2.5 2.5	0.5 0.5	2.5 2.5	ns	CL = 50 pF
t <sub>S</sub>	Setup Time SEL to D		1.0		1.0		1.0		ns	

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

**Table 8. DUTY CYCLE SPECIFICATIONS** ( $0^{\circ}C \le T_A \le 85^{\circ}C$ ; Duty Cycle Measured Relative to 1.5 V)

Symbol	Characteristic		Min	Nom	Max	Unit	Condition
PW	Range of V <sub>CC</sub> and CL to Meet Min Pulse Width (HIGH or LOW) at f <sub>out</sub> ≤50MHz	V <sub>CC</sub> CL PW	4.875 10.0 9.0	5.0	5.125 50.0 11.0	V pF ns	All Outputs

#### **ORDERING INFORMATION**

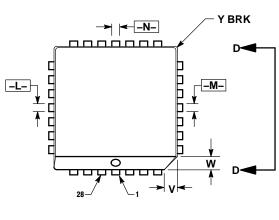
Device	Package	Shipping <sup>†</sup>
MC10H645FNG	PLCC-28 (Pb-Free)	37 Units / Rail
MC10H645FNR2G	PLCC-28 (Pb-Free)	500 / Tape & Reel

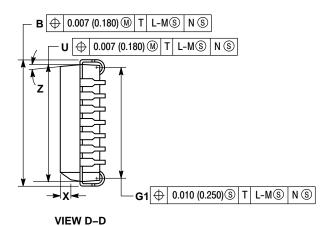
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>Within-Device Skew defined as identical transitions on similar paths through a device.

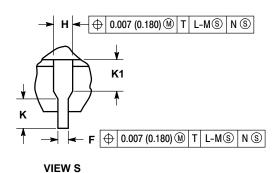
#### PACKAGE DIMENSIONS

#### PLCC-28 **FN SUFFIX** CASE 776-02 ISSUE E





⊕ 0.007 (0.180) M T L-MS N S  $\oplus$ 0.007 (0.180) M T L-MS N S C Ε ☐ 0.004 (0.100) -T- SEATING VIEW S G1 ⊕ 0.010 (0.250)⑤ T L-M⑥ N ⑥



#### NOTES:

- IOTES:

  1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE
- MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

  4. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
   THE PACKAGE TOP MAY BE SMALLER THAN
   THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, THE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY. PLASTIC BODY
- 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.485	0.495	12.32	12.57
В	0.485	0.495	12.32	12.57
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020	-	0.50
Z	2 °	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040		1.02	

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